



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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SURFBOARDS[®]

THE BREADBOARDING MEDIUM FOR **SURFACE MOUNT**™



33000 SERIES APPLICATION SPECIFIC ADAPTERS

IDS33306
REV A-10-2011

MODEL **33306**

ACCEPTS
(PARTIAL LISTING)

ON SEMI

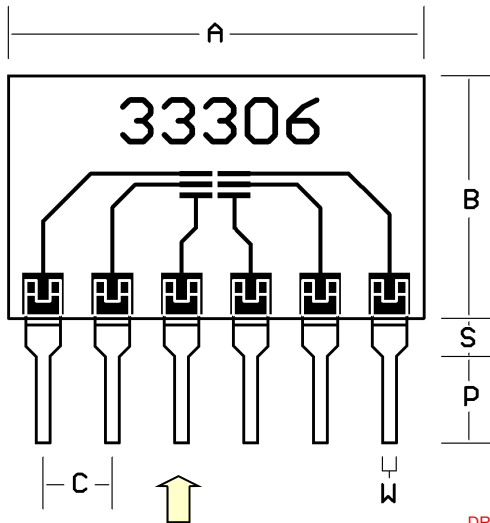
ULLGA6 1.2x1.0,0.4P
WDFN6 1.2x1.0,0.4P
WDFN6 1.25x1.0,0.4P

6 LEAD .4 mm PITCH DEVICES

DEVICE LEAD WIDTH 1.0 To Max 2.3 MM

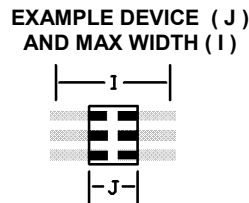
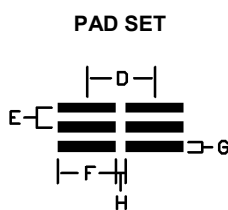
RENESAS **6L2MM (1208 PKG)**

ALWAYS CONSULT DEVICE DATA SHEET TO INSURE PROPER FIT



**SINGLE-IN-LINE (SIP) PINS
ON .100 in. CENTERS**

DRAWINGS
NOT TO
SCALE



MOUNTING PADS ARE OVSIZED IN LENGTH TO ACCEPT A WIDER RANGE OF DEVICE WIDTHS AND TOLERANCES AND TO PERMIT HAND SOLDERING.

[SEE WEBSITE FOR SOLDERING SUGGESTIONS](#)

Pins on .1 in. Centers designed for use with Solderless breadboards, Conventional Breadboards, and Sockets with standard .1 in. centers.

Use For Prototyping, Device Test or Evaluation and SMD to Through Hole Conversion.

Oversize Pads Permit hand soldering and accept a wide range of device widths and tolerances.

FIG.	MM	IN.	NOTE:
A	15.24	.600	BOARD WIDTH +- .5mm .020in.
B	8.89	.350	BOARD HEIGHT +- .5mm .020in.
C	2.54	.100	SIP PIN SPACE +- .20mm .008in.
D	1.4	.055	PAD CENTERLINE
E	.4	.016	DEVICE LEAD PITCH
F	1.2	.047	PAD LENGTH
G	.22	.009	PAD WIDTH
H	.2	.008	GAP
I	2.3	.090	MAX LEAD WIDTH
J	1.0	.039	TYPICAL LEAD WIDTH
P	3.3	.130	LENGTH FROM SHOULDER +- .5mm .020in.
S	1.57	.062	PIN SHOULDER HEGHT
W	.5	.020	PIN WIDTH

TOLERANCES: If not noted are +- 20%. Nominal values are given. Controlling unit is Millimeters. Slight Variations due to manufacturing process can occur.

BOARD SPECIFICATIONS

BOARD MATERIAL: .8mm, +- .13mm .031in+- .005 in. Thick G-10 FR-4 Glass Epoxy or equivalent.

CIRCUITS: 1 oz. Copper with RoHS compliant Lead Free solder coating. Patten Position on board +- .5mm .020in.



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